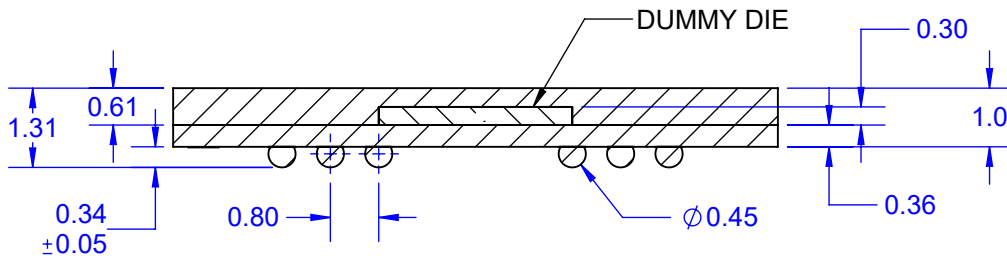
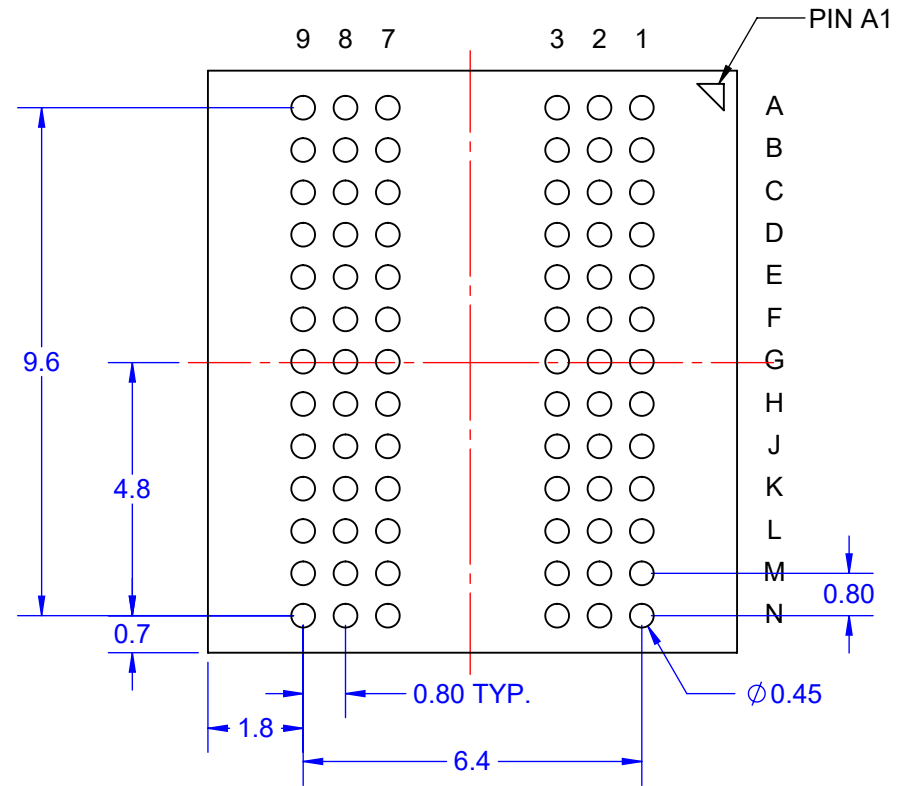
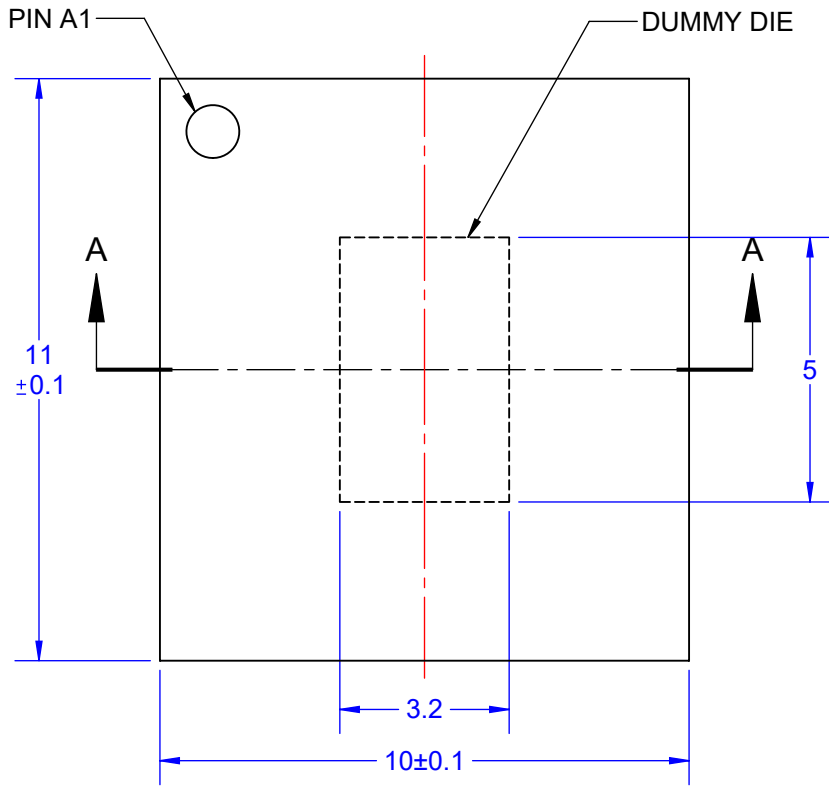


HCD J9K

65 @@J9K




SECTION A-A
SCALE 8 : 1

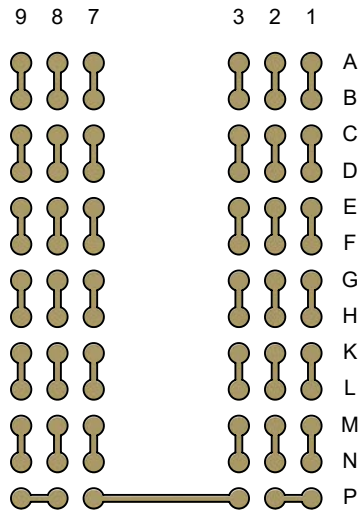
Notes: Unless Otherwise Specified).

- 1) ALL DIMENSIONS ARE IN MM.
- 2) SOLDER BALL ALLOY: SEE PART NUMBER TABLE.
- 3) BALL DIAMETER (BEFORE REFLOW): 0.50mm.
- 4) SOLDER MASK DEFINED PAD OPENING: 0.42mm (16.5 MIL).
- 5) PAD Cu DIAMETER: 0.50mm (19.7 MIL).
- 6) SUBSTRATE MATERIAL: BT (ALTERNATE FR4).
- 7) DUMMY DIE IS OPTIONAL.
- 8) DAISY CHAIN PATTERN (SEE PAGE 2).
- 9) MSL-3 RECOMMENDED BAKING 24 HOURS @ 125°C TO REMOVE MOISTURE PRIOR TO SOLDERING TO PC BOARD.

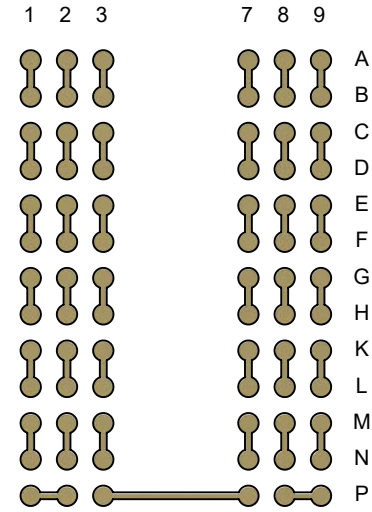
D5 FH'BI A69F H56 @				
D5 FH'BI A69F	65 @@5 @CM	65 @@7 C89	Fc<G	GJ'8-9
BGA78T.8C-DC635D	Sn96.5/Ag3.0/Cu0.5	SAC305	YES	YES
BGA78T.8-DC635D	Sn63/Pb37	Sn63	NO	YES

APPROVALS	DATE				
DRAWN T.Au	6/11/2021				
ENG M. Hart	6/11/2021	TITLE BGA78T.8C-DC635D DAISY CHAIN			
MFG					
QA		SCALE	SIZE	DRAWING NO.	REV
CUST		7:1	A	586353	A
REVISED		DO NOT SCALE DRAWING			SHEET 1 OF 3

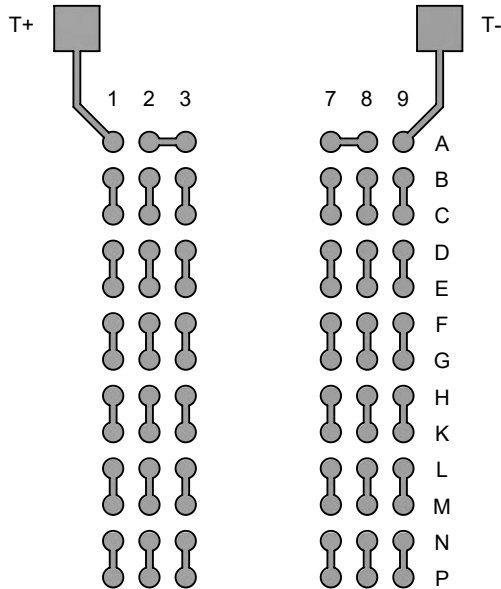
65 @J-K



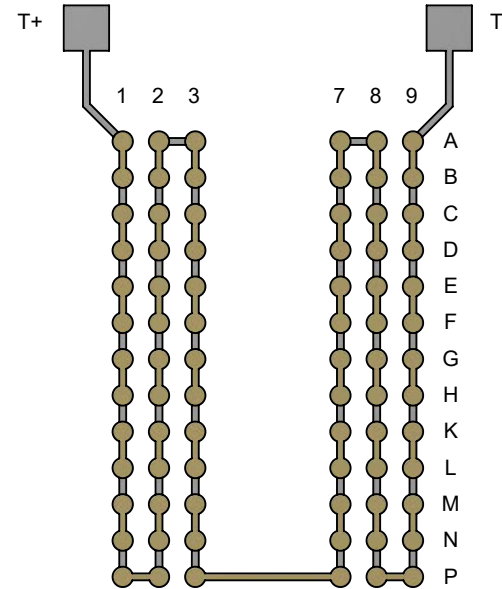
6 CHCA 'G-89 'fHCD'L!F5 MJ-K L



H9GH'J9<7 @ '6 C5 F8



5: H9F 'ACI BH-B;



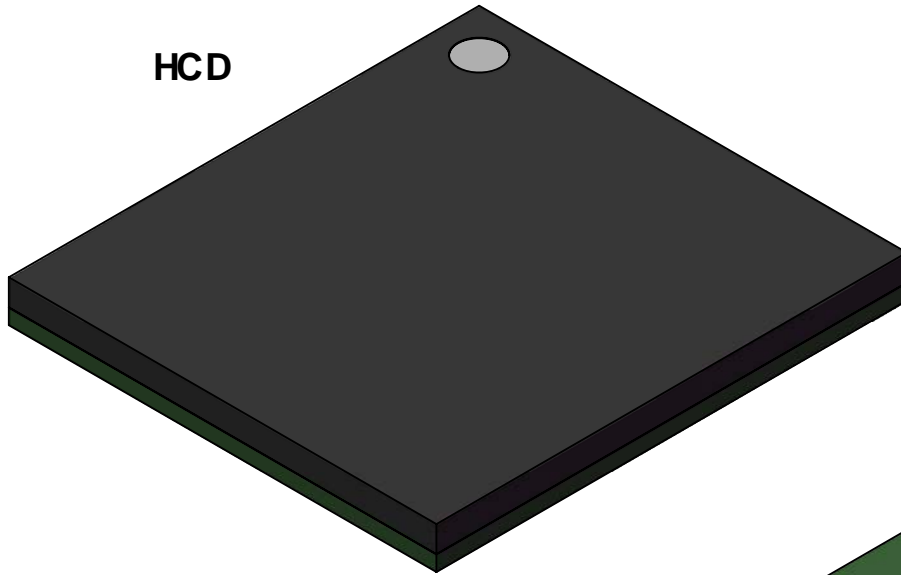
Notes:

- 1) PCB BOARD DIMENSIONS ARE PRESENTED ONLY AS A GUIDELINE. DESIGNERS SHOULD USE THEIR OWN EXPERIENCE WHEN DESIGNING PCB.
- 2) PCB Cu BALL PAD DIAMETER: 0.5mm (19.7 MIL).
- 3) PCB DAISY CHAIN TRACING LINE WIDTH 0.152mm (6 MIL).
- 4) SMD (SOLDER MASK DEFINED) PAD OPENING: 0.42mm (16.5 MIL).

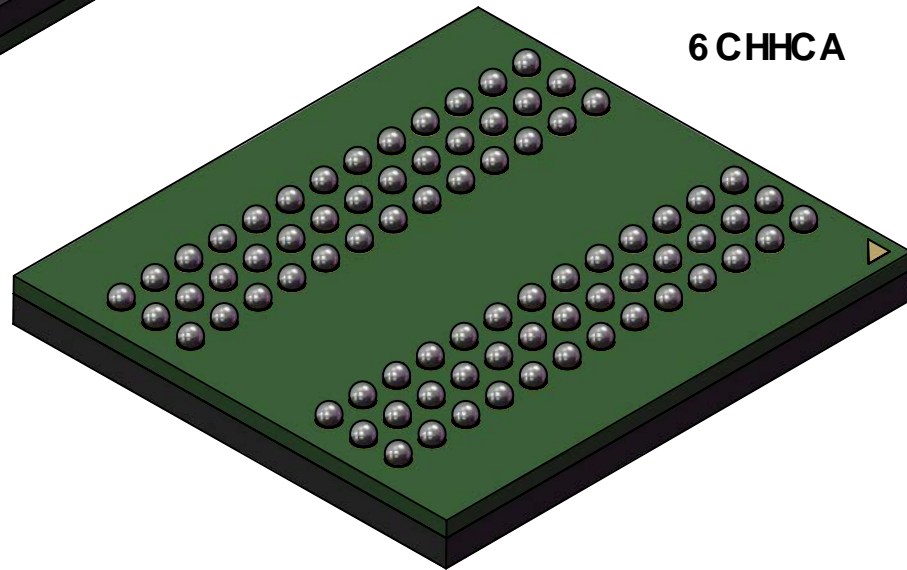
TopLine[®]			
TITLE		BGA78T.8C-DC635D DAISY CHAIN	
SCALE	SIZE	DRAWING NO.	REV
6:1	A	586353	A
DO NOT SCALE DRAWING			SHEET 2 OF 3

AC89@

HCD



6 CHCA



TopLine[®]

TITLE BGA78T.8C-DC635D
DAISY CHAIN

SCALE 8:1	SIZE A	DRAWING NO. 586353	REV A
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DO NOT SCALE DRAWING

SHEET 3 OF 3